

PATENT ABSTRACTS OF JAPAN

(11)Publication number : **2001-024374**

(43)Date of publication of application : **26.01.2001**

(51)Int.CI.

H05K 7/20
F28D 15/02

(21)Application number : **11-195940**

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(22)Date of filing : **09.07.1999**

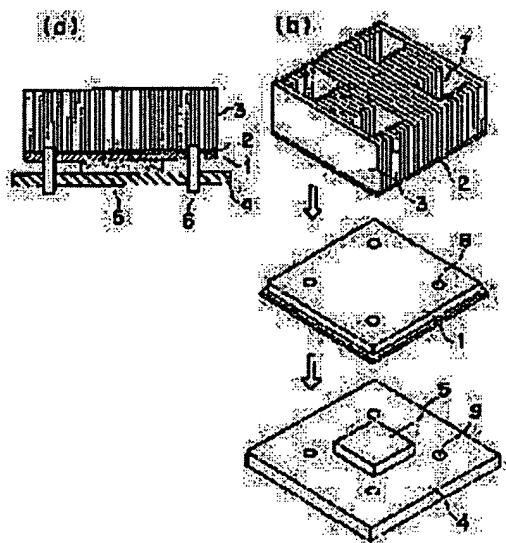
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(54) HEAT SINK FOR ELECTRICAL HEATING ELEMENT GENERATING HEAT IN HIGH DENSITY

(57)Abstract:

PROBLEM TO BE SOLVED: To efficiently cool the semiconductor element of miniaturized electric equipment by integrally fixing a vapor chamber and a high-strength heat radiation member for improving the strength to an electrical heating element.

SOLUTION: A plate-type heat pipe 1 for composing a vapor chamber is made of a container with a cavity that is sealed, for example, by upper and lower plate materials made of copper, a hole 8 for such fixing member as a screw is formed also at a container, and for example, water is sealed into the sealed cavity member of the container as working fluid. A plate-type heat pipe 1 and a heat sink are overlapped onto electrical heating part placement member 4 where electrical heating parts 5 are placed and are fixed integrally by such fixing member as a screw through the holes 7, 8 and 9, thus strongly pressing the plate-type heat pipe 1 to the electrical heating parts 5 without any deformation by a base with the sufficient bending strength of the heat sink and obtaining high heat performance.



LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]